



Transient Voltage Suppressors for ESD Protection General Description

The S-LESD8D5.0CB1T5G is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, digital cameras and many other portable applications where board space is at a premium.

Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

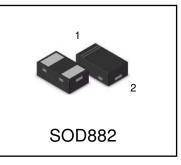
Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 85 Watts @ 8 x 20 μs
 Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- We declare that the material of product compliance with RoHS requirements.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power ($t_p = 8/20 \ \mu \ s$)	85	W	
ΤL	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +155	°C	
T_{op}	Operating Temperature Range	-40 to +150	°C	
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) ai	r discharge	±30	
	contac	t discharge	±30	KV

S-LESD8D5.0CB1T5G





Ordering information

Device	Marking	Shipping
S-LESD8D5.0CB1T5G	U2	10000/Tape&Reel

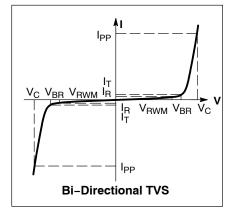


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Electrical Parameter

(T_A = 25°C unless otherwise noted)

Symbol	Parameter
I _{PP}	Maximum Reverse Peak Pulse Current
V _C Clamping Voltage @ I _{PP}	
V _{RWM}	Working Peak Reverse Voltage
I _R	Maximum Reverse Leakage Current @ $\mathrm{V}_{\mathrm{RWM}}$
V _{BR} Breakdown Voltage @ I _T	
Ι _Τ	Test Current
P _{pk}	Peak Power Dissipation
С	Capacitance @ $V_R = 0$ and f = 1.0 MHz



Electrical Characteristics

Device	V _{RWM} (V)	I _R (μΑ) @ V _{RWM}		/) @ I _T te 1)	ե	V _C (V) @ Ipp = 1 A	V _C (V) @ I _{PP} = 8 A	I _{PP} (A)	P _{PK} (W)	C (pF)
Device	Мах	Max	Min	Мах	mA	Max	Max	Max	Max	Max
S-LESD8D5.0CB1T5G	5.0	0.5	5.6	8	1.0	8.5	9	10	85	25

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25° C.

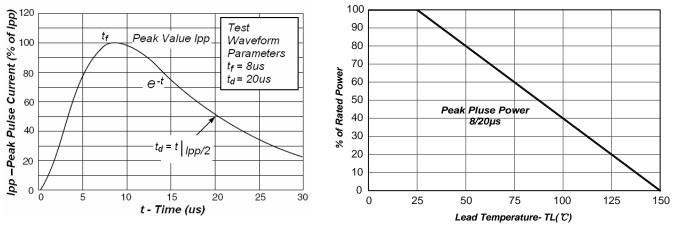










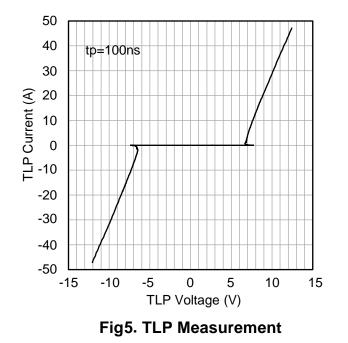


Figure 3. Positive 8kV contact per IEC 61000-4-2

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Fig 4. Negative 8kV contact per IEC 61000-4-2



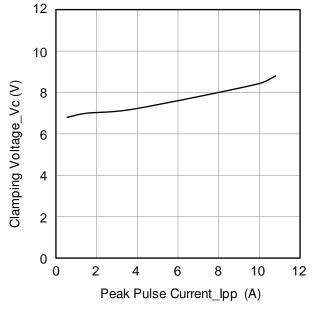
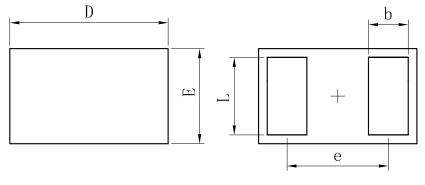


Fig6 .Clamping Voltage vs. Peak Pluse Current



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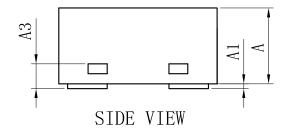
OUTLINE AND DIMENSIONS



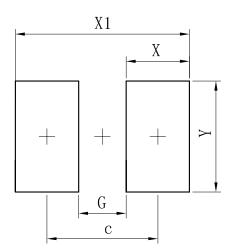
TOP VIEW



SOD882					
Dim	Min	Тур	Max		
D	0.95	1.00	1.05		
Е	0.55	0.60	0.65		
е	-	0.64	-		
L	0.44	0.49	0.54		
b	0.20	0.25	0.30		
A	0.43	0.48	0.53		
A1	0 – 0.05				
A3	0.127REF.				
All Dimensions in mm					



SOLDERING FOOTPRINT



Dimensions	(mm)
С	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70



DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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